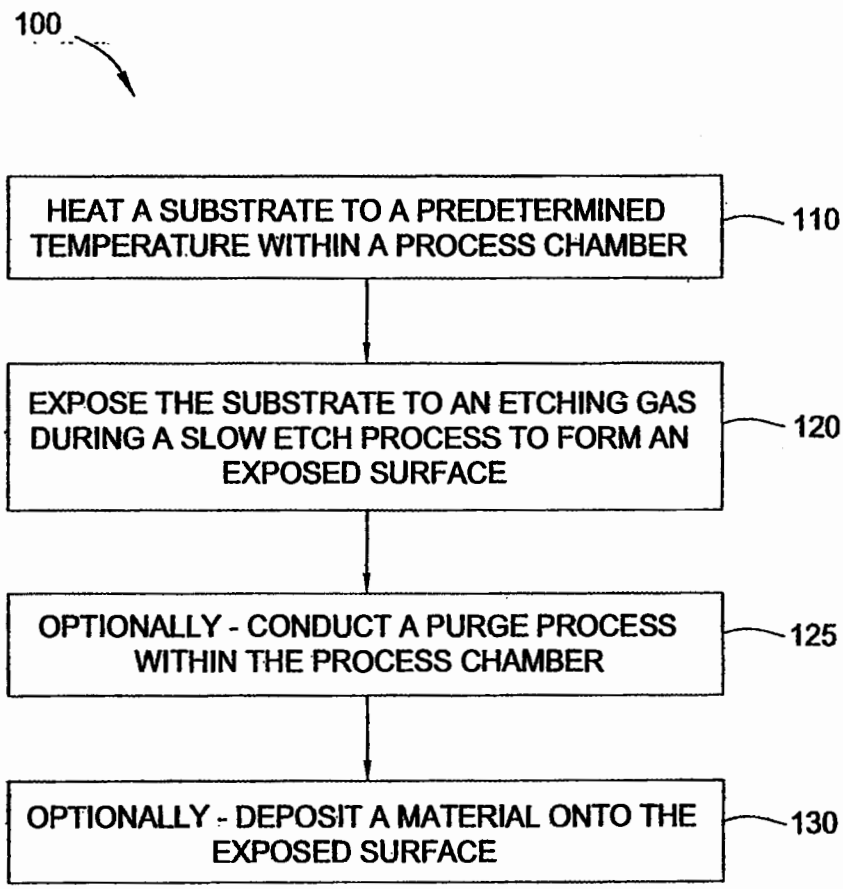

100
HEAT A SUBSTRATE TO A PREDETERMINED TEMPERATURE WITHIN A PROCESS CHAMBER
110
EXPOSE THE SUBSTRATE TO AN ETCHING GAS DURING A SLOW ETCH PROCESS TO FORM AN EXPOSED SURFACE
120
OPTIONALLY - CONDUCT A PURGE PROCESS WITHIN THE PROCESS CHAMBER
125
OPTIONALLY - DEPOSIT A MATERIAL ONTO THE EXPOSED SURFACE
130

FIG. 1

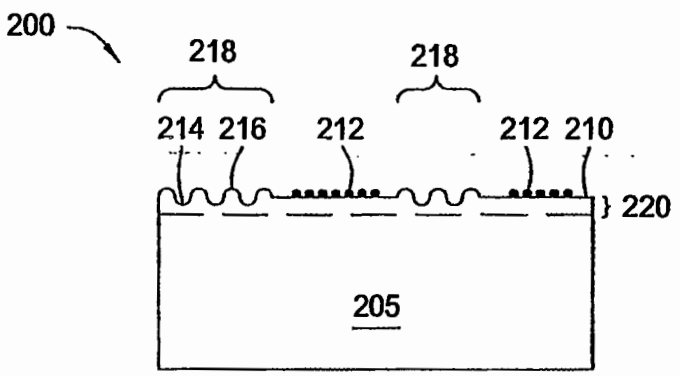


FIG. 2A

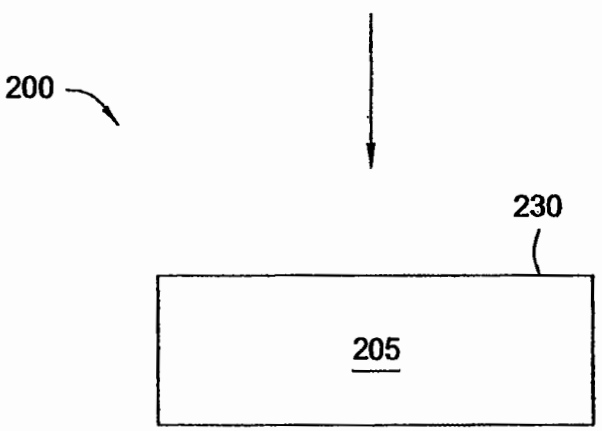


FIG. 2B

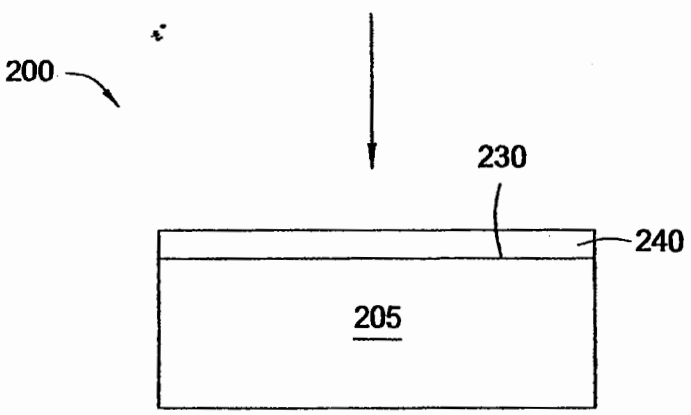


FIG. 2C

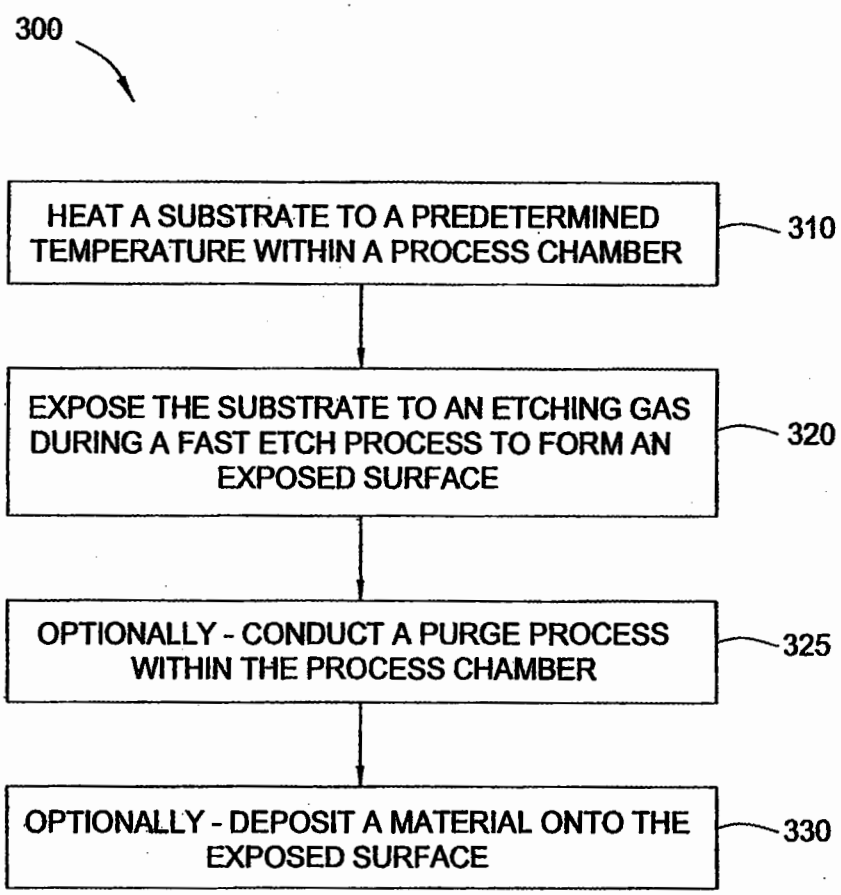

300
HEAT A SUBSTRATE TO A PREDETERMINED TEMPERATURE WITHIN A PROCESS CHAMBER
310
EXPOSE THE SUBSTRATE TO AN ETCHING GAS DURING A FAST ETCH PROCESS TO FORM AN EXPOSED SURFACE
320
OPTIONALLY - CONDUCT A PURGE PROCESS WITHIN THE PROCESS CHAMBER
325
OPTIONALLY - DEPOSIT A MATERIAL ONTO THE EXPOSED SURFACE
330

FIG. 3

FIG. 4A

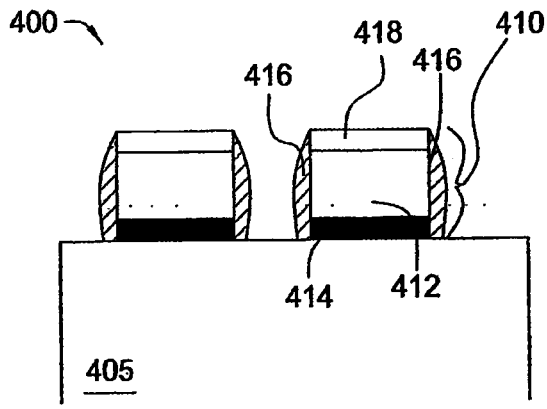


FIG. 4B

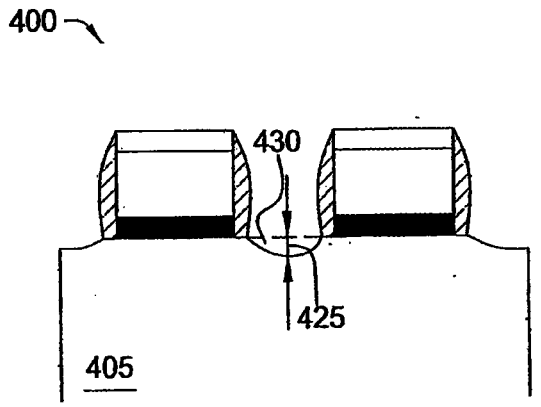
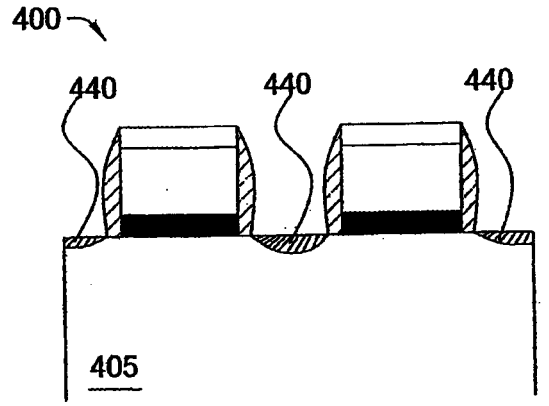


FIG. 4C



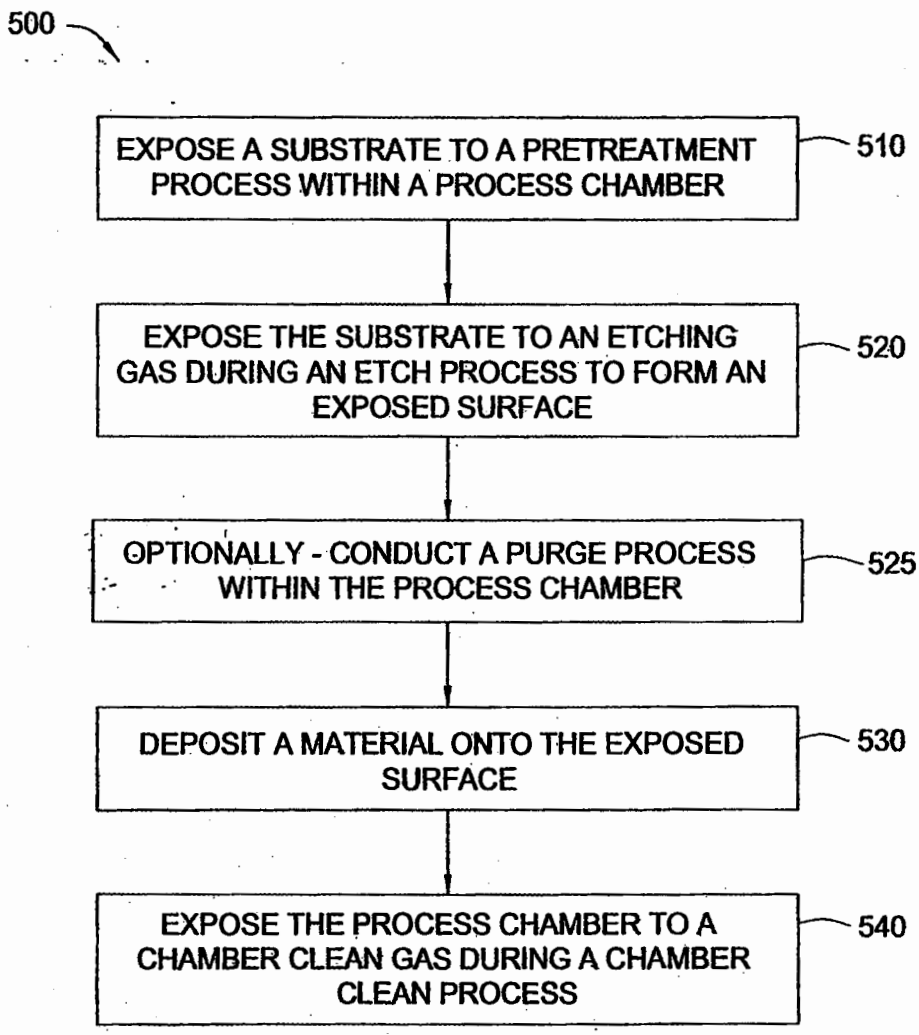

500
EXPOSE A SUBSTRATE TO A PRETREATMENT PROCESS WITHIN A PROCESS CHAMBER
510
EXPOSE THE SUBSTRATE TO AN ETCHING GAS DURING AN ETCH PROCESS TO FORM AN EXPOSED SURFACE
520
OPTIONALLY - CONDUCT A PURGE PROCESS WITHIN THE PROCESS CHAMBER
525
DEPOSIT A MATERIAL ONTO THE EXPOSED SURFACE
530
EXPOSE THE PROCESS CHAMBER TO A CHAMBER CLEAN GAS DURING A CHAMBER CLEAN PROCESS
540

FIG. 5